



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICATION NO. : 10/725,933  
APPLICANT : Yang et al.  
FILED : December 3, 2003  
FOR : FAN OUT TYPE WAFER LEVEL PACKAGE  
STRUCTURE AND METHOD OF THE SAME  
CONFIRMATION NO. : 4487  
ART UNIT : 2891  
EXAMINER : David A. Zarneke  
ATTORNEY DOCKET NO. : HK9225US

February 26, 2008

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**RESPONSE TO OFFICE ACTION**

Dear Sir:

In response to the Office Action dated October 29, 2007, please amend the above-identified application as follows:

**Amendments to the Specification** begin on page 2 of this paper.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 3 of this paper.

**Remarks/Arguments** begin on page 7 of this paper.